

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings of claims in the application:

**Listing of Claims:**

1-17. (canceled)

18. (currently amended) A method as in claim 24 wherein step (b) advances curing of the thermosetting epoxy resin.

19-20. (canceled)

21. (previously presented) A method as in claim 24 wherein the semiconductor device comprises an integrated circuit.

22. (previously presented) A method as in claim 24 wherein step (a) includes a transfer molding process.

23. (previously presented) A method as in claim 24 wherein step (a) includes a potting process.

24. (currently amended) A method of making a semiconductor device to be soldered with an Sn-Ag-Cu type solder to a substrate, the method comprising:

(a) sealing the semiconductor device in a package by surrounding it with thermosetting epoxy resin and thermally curing the resin at a first temperature;

(b) baking the thermosetting epoxy resin at a second temperature not higher than the first temperature;

(c) further baking the thermosetting epoxy resin at a third temperature higher than the first temperature, wherein the third temperature is between about 220°C and about 260°C; and

(d) inspecting the semiconductor device.

25. (previously presented) A method as in claim 24 wherein a conductive lead is adhesively affixed to a main surface of the semiconductor device.

26. (previously presented) A method as in claim 25 wherein the conductive lead is adhesively affixed to a peripheral portion of the main surface of the semiconductor device.

27. (previously presented) A method as in claim 26 wherein an electrode of the semiconductor device is electrically connected to the conductive lead.

28-30. (canceled)